# PRODUCT SPECIFICATIONS

AIEMC

## BMLB160808 — SERIE

CUSTOMER'S PRODUCT NAME:

DATE: 2026.07

### SPEC. NO: B-2607-16

**THIS SPECIFICATION IS:**

- ○ FULLY ACCEPTED
- ○ DENIED
- ○ ACCEPTED UNDER THE FOLLOWING CONDITIONS :

SIGNATURE: DATE:

NAME(PRINT): TITLE:

REACH COMPLIANT

RoHS COMPLIANT

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TEL: 03-5894-433 FAX: 03-5894-523

## ① Features

- For Power Line
- Reduced power loss and improved system efficiency
- Improved signal integrity
- Compliance with EMI regulations

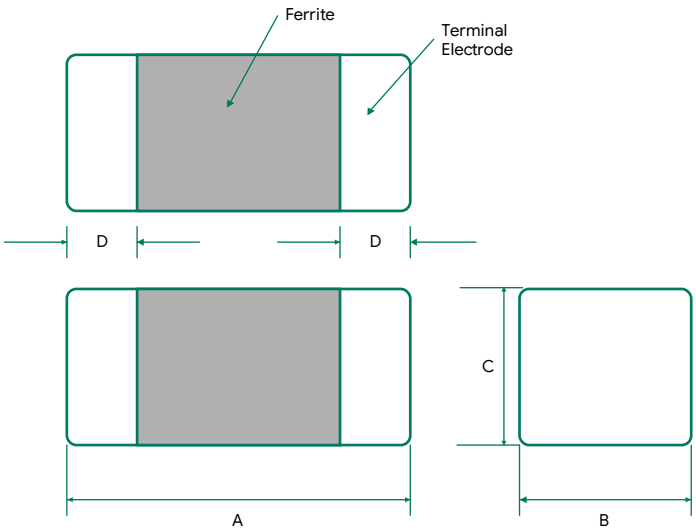
## ② Application

- Wearable device
- Industrial
- Communications
- Consumer Electronics

## ③ Part numbering

| B | – | MLB | – | 160808 | – | □□□ | – | Y | – | 00 |
|---|---|---|---|---|---|---|---|---|---|---|
| Grade | | Product Series | | Dimensions(mm) | | Impendance (Ω) | | Tolerance | | Control code |

## ④ Appearance and Dimensions




Dimensions in mm

| | |
|---|---|
| **A** 1.60 ± 0.15 | **B** 0.80 ± 0.15 |
| **C** 0.80 ± 0.15 | **D** 0.30 ± 0.20 |

## ⑤ Rating

⚠ NOTE Operating Temperature Range : -55 to +125°C

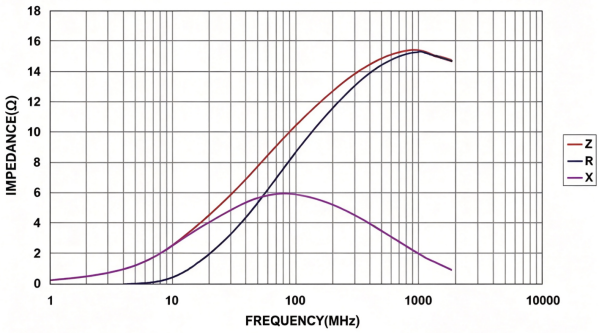
## ELECTRICAL CHARACTERISTICS

| Part No. | Impedance (Ω ± 25%) | Test Freq (Hz/mV) | DCR (Ω)Max | RatedCurrent (mA)Max |
|---|---|---|---|---|
| BMLB160808100Y00 | 10 | 100 MHz/200 mV | 0.02 | 4000 |
| BMLB160808110Y00 | 11 | 100 MHz/200 mV | 0.02 | 4000 |
| BMLB160808190Y00 | 19 | 100 MHz/200 mV | 0.03 | 3000 |
| BMLB160808220Y00 | 22 | 100 MHz/200 mV | 0.03 | 3000 |
| BMLB160808250Y00 | 25 | 100 MHz/200 mV | 0.03 | 3000 |
| BMLB160808260Y00 | 26 | 100 MHz/200 mV | 0.03 | 3000 |
| BMLB160808300Y00 | 30 | 100 MHz/200 mV | 0.03 | 3000 |
| BMLB160808330Y00 | 33 | 100 MHz/200 mV | 0.035 | 3000 |
| BMLB160808400Y00 | 40 | 100 MHz/200 mV | 0.035 | 3000 |
| BMLB160808470Y00 | 47 | 100 MHz/200 mV | 0.04 | 3000 |
| BMLB160808500Y00 | 50 | 100 MHz/200 mV | 0.04 | 3000 |
| BMLB160808600Y00 | 60 | 100 MHz/200 mV | 0.04 | 3000 |
| BMLB160808680Y00 | 68 | 100 MHz/200 mV | 0.05 | 2500 |
| BMLB160808700Y00 | 70 | 100 MHz/200 mV | 0.05 | 2500 |
| BMLB160808750Y00 | 75 | 100 MHz/200 mV | 0.05 | 2500 |
| BMLB160808800Y00 | 80 | 100 MHz/200 mV | 0.05 | 2500 |
| BMLB160808101Y00 | 100 | 100 MHz/200 mV | 0.05 | 2500 |
| BMLB160808121Y00 | 120 | 100 MHz/200 mV | 0.08 | 2500 |
| BMLB160808151Y00 | 150 | 100 MHz/200 mV | 0.085 | 2000 |

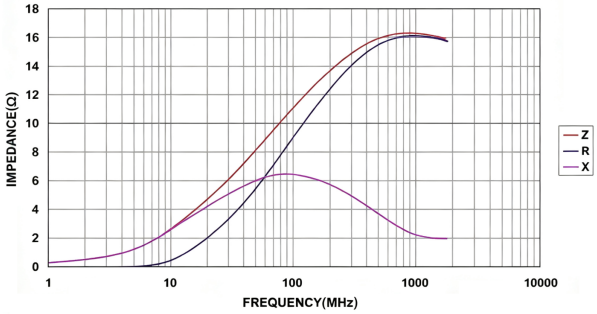
| Part No. | Impedance (Ω ± 25%) | Test Freq (Hz/mV) | DCR (Ω)Max | RatedCurrent (mA)Max |
|---|---|---|---|---|
| BMLB160808181Y00 | 180 | 100 MHz/200 mV | 0.09 | 2000 |
| BMLB160808201Y00 | 200 | 100 MHz/200 mV | 0.095 | 2000 |
| BMLB160808221Y00 | 220 | 100 MHz/200 mV | 0.10 | 2000 |
| BMLB160808241Y00 | 240 | 100 MHz/200 mV | 0.12 | 1500 |
| BMLB160808301Y00 | 300 | 100 MHz/200 mV | 0.12 | 1500 |
| BMLB160808331Y00 | 330 | 100 MHz/200 mV | 0.12 | 1500 |
| BMLB160808471Y00 | 470 | 100 MHz/200 mV | 0.15 | 1500 |
| BMLB160808601Y00 | 600 | 100 MHz/200 mV | 0.20 | 1000 |
| BMLB160808102Y00 | 1000 | 100 MHz/200 mV | 0.25 | 800 |
| BMLB160808122Y00 | 1200 | 100 MHz/200 mV | 0.25 | 800 |
| BMLB160808152Y00 | 1500 | 100 MHz/200 mV | 0.40 | 500 |

# Typical Eleectrical Characteristics

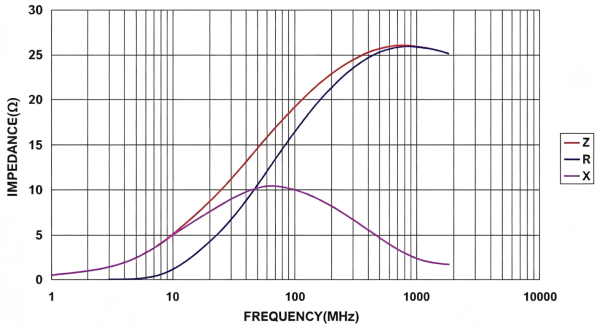
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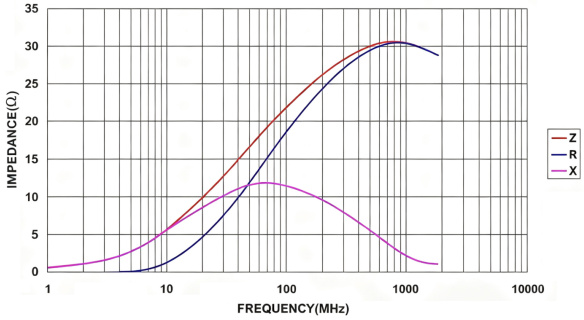

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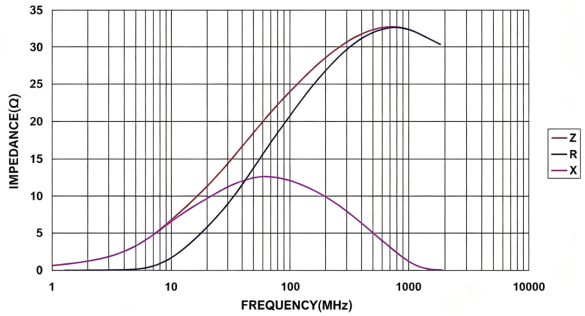

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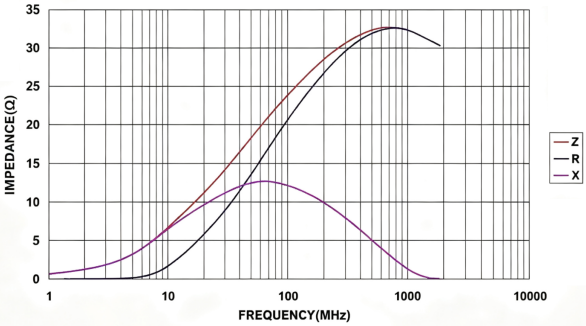

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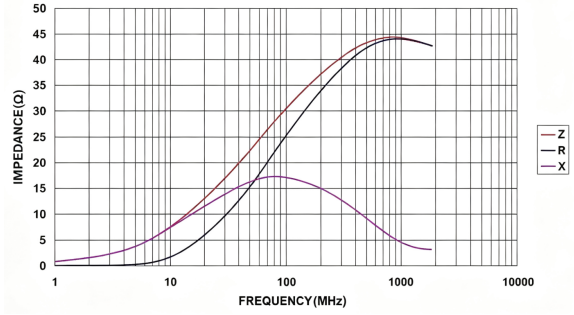

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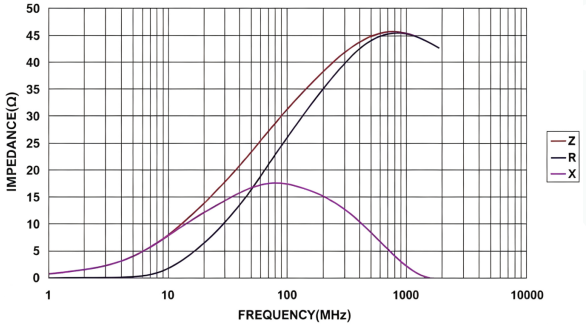

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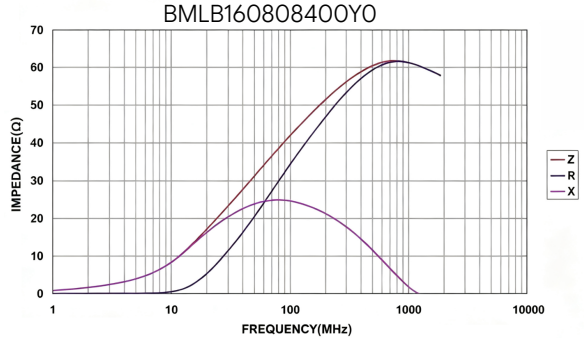



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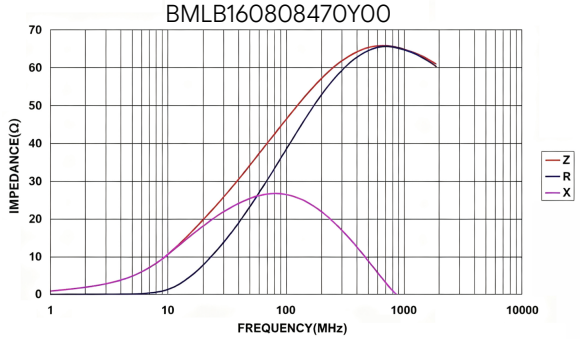


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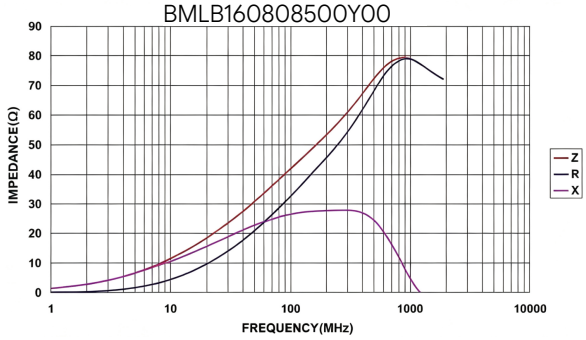
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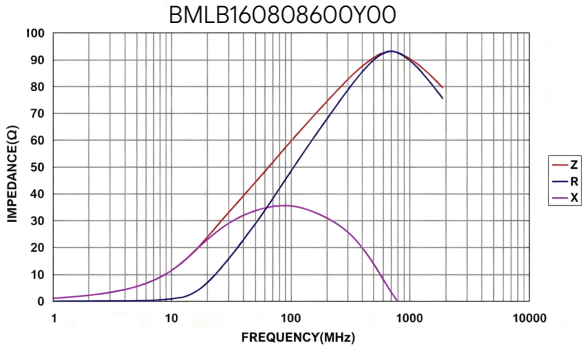

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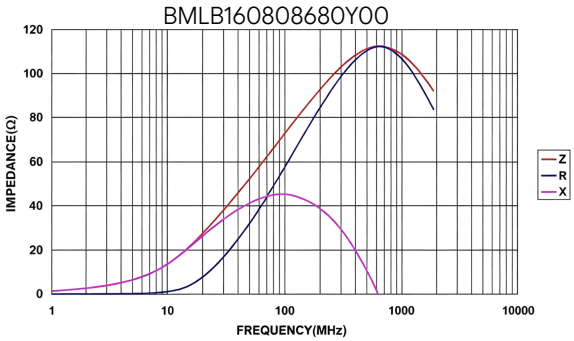

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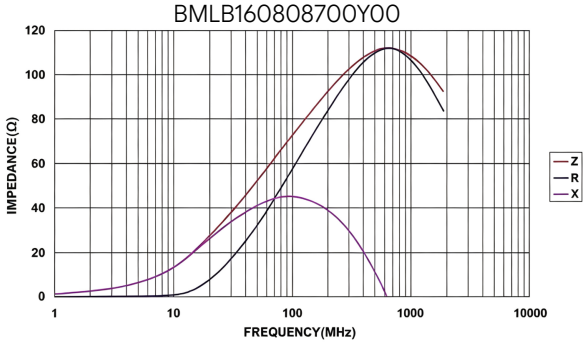

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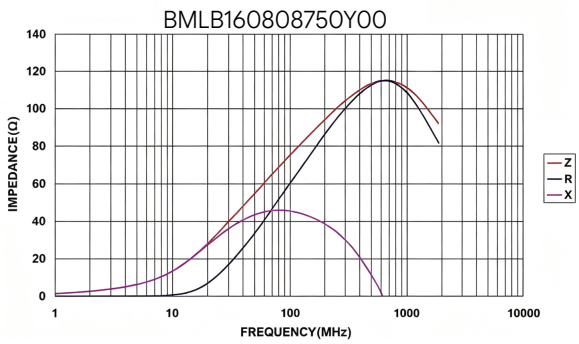

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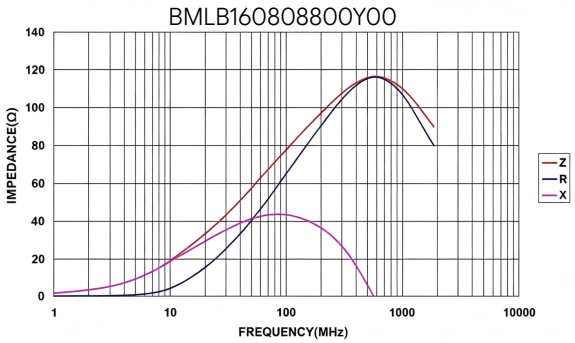

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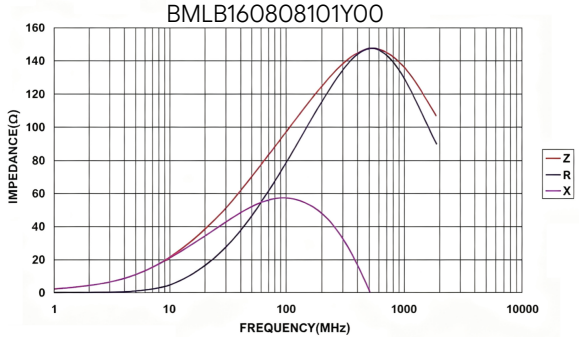



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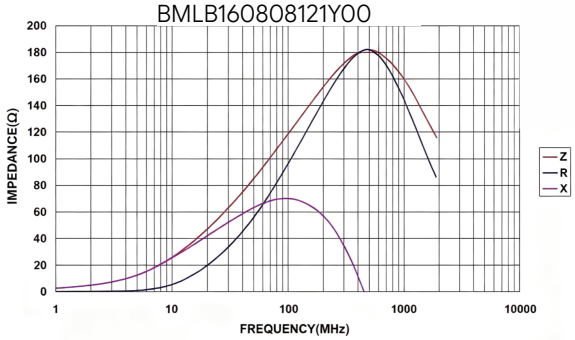


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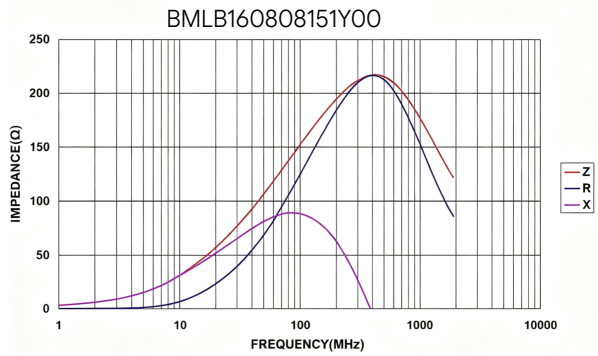
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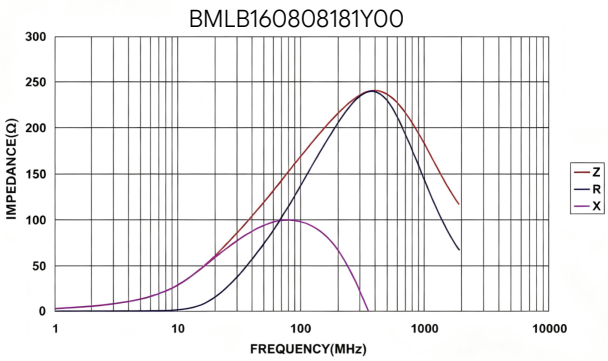

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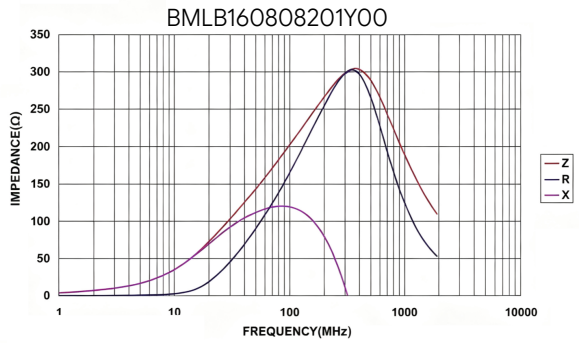

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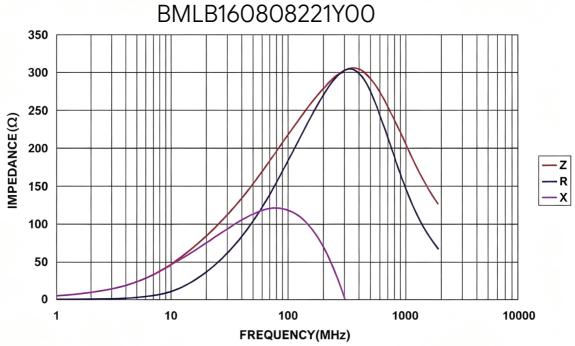

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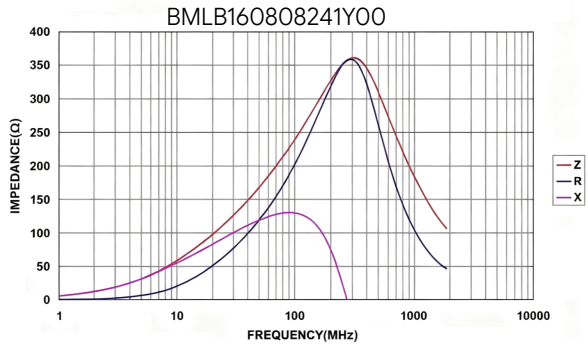

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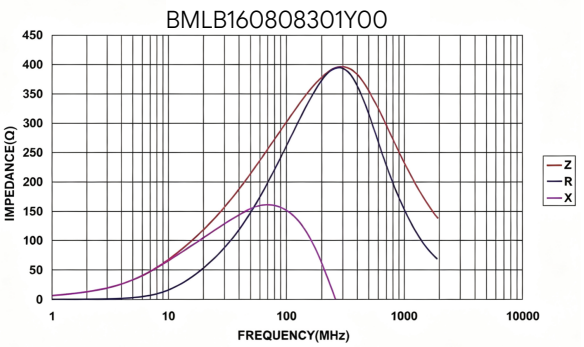

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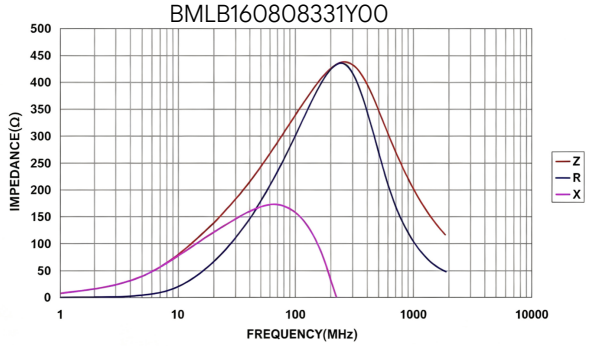



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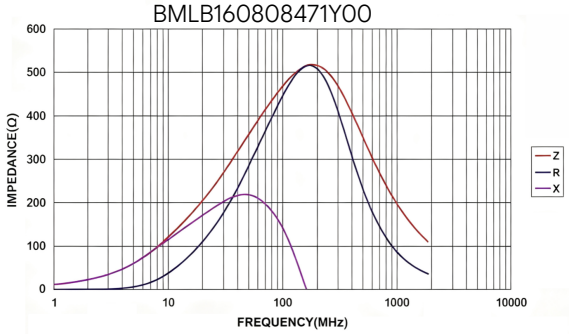


# Typical Eleectrical Characteristics

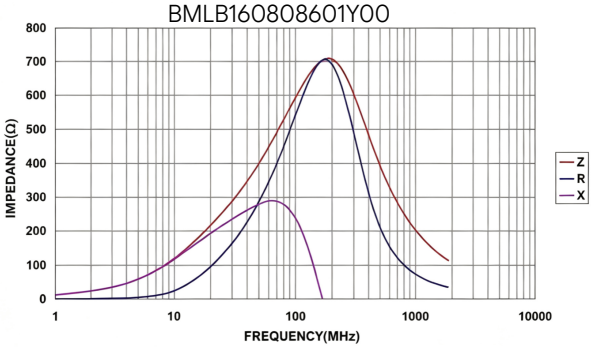
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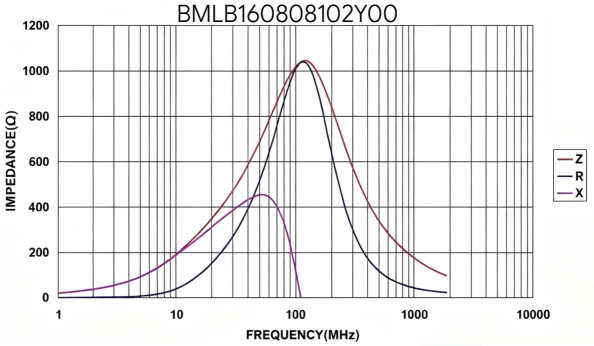

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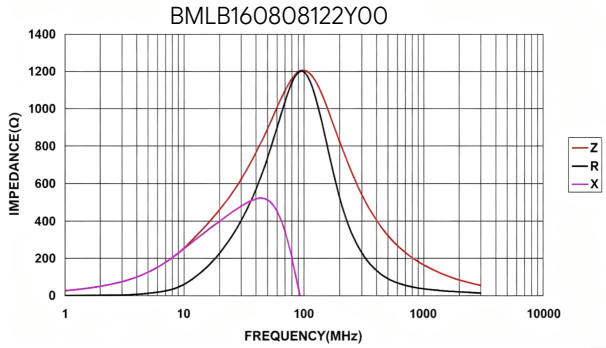

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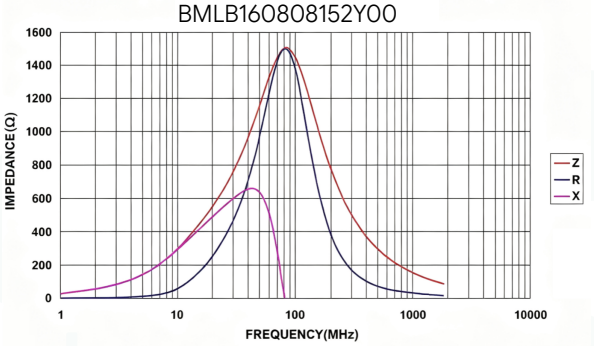

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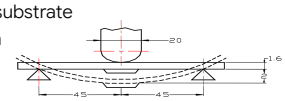
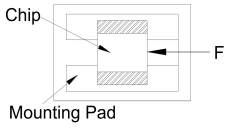



BMLB160808152Y00



## ⑥ Reliable Performance

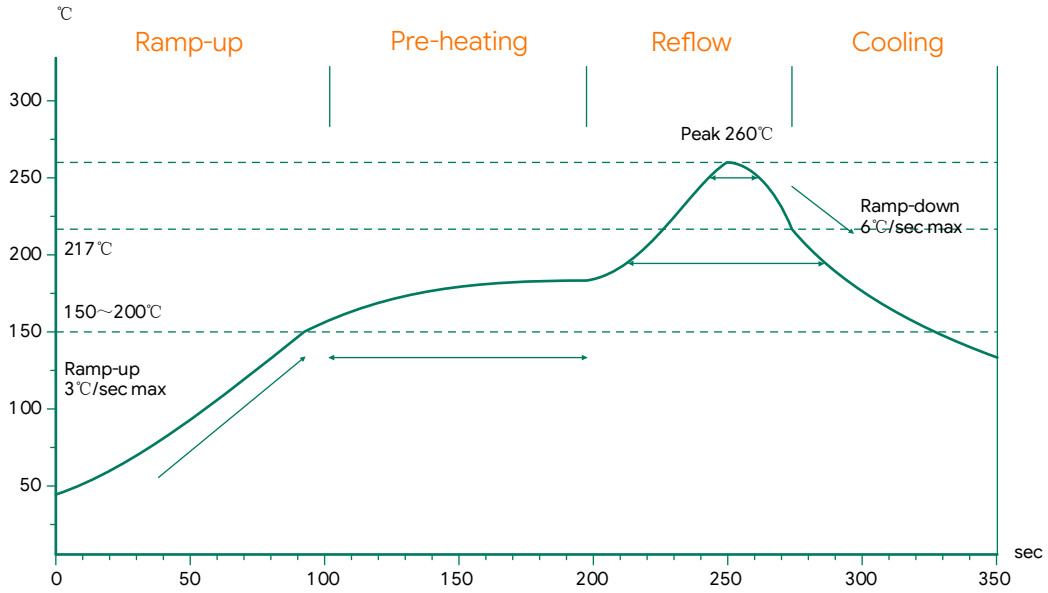
### 1-1 Mechanical Performance

| No | Item | Specification | Test Method |
|---|---|---|---|
| 1-1-1 | Flexure Strength | The forces applied on the right conditions must not damage the terminal electrode and theferrite | Test device shall be soldered on the substrate<br>Substrate Dimension: 100x40x1.6mm<br>Deflection: 2.0mm<br>Keeping Time: 30sec<br>*For 100505, substrate dimension is 100x40x0.8mm<br>  |
| 1-1-2 | Vibration | | Test device shall be soldered on the substrate<br>Oscillation Frequency: 10 to 55 to 10Hz for 1min<br>Amplitude: 1.5mm<br>Time: 2hrs for each axis (X, Y & Z), total 6hrs |
| 1-1-3 | Resistance to Soldering Heat | Appearance: No damage<br>More than 75% of the terminal electrode should be covered with solder.<br>Impedance : within ±30% of initial value | Pre-heating: 150℃, 1min<br>Solder Composition: Sn/Ag3.0/Cu0.5(Pb-Free)<br>Solder Temperature: 260±5℃<br>Immersion Time: 10±1sec |
| 1-1-4 | Solder ability | The electrodes shall be at least 95% covered with new solder coating | Pre-heating: 150℃, 1min<br>Solder Composition: Sn/Ag3.0/Cu0.5(Pb-Free)<br>Solder Temperature: 245±5℃(Pb-Free)<br>Immersion Time: 4±1sec |
| 1-1-5 | Terminal Strength Test | No split termination<br>  | Test device shall be soldered on the substrate, then apply a force in the direction of the arrow.<br>Force: 5N<br>Keeping Time: 10 ± 1sec |

### 1-2 Environmental Performance

| No | Item | Specification | Test Method |
|---|---|---|---|
| 1-2-1 | Temperature Cycle | Appearance: No damage<br>Impedance: within±30% of initial value | One cycle:<br>Step / Temperature (°C) / Time (min)<br>1 / -55±3 / 30<br>2 / 25±2 / 3<br>3 / 125±3 / 30<br>4 / 25±2 / 3<br>Total: 100cycles<br>Measured after exposure in the room condition for 24hrs |
| 1-2-2 | Humidity Resistance | | Temperature: 40±2°C<br>Relative Humidity: 90 ~ 95% / Time: 1000hrs<br>Measured after exposure in the room condition for 24hrs |
| 1-2-3 | High Temperature Resistance | | Temperature: 125±3°C / Relative Humidity: 0%<br>Applied Current: Rated Current /Time: 1000hrs<br>Measured after exposure in the room condition for 24hrs |
| 1-2-4 | Low Temperature Resistance | | Temperature: -55±3°C<br>Relative Humidity: 0% / Time: 1000hrs<br>Measured after exposure in the room condition for 24hrs |

## ⑦ Recommended Soldering Conditions




Reflow profile

**Lead-Free (LF)** **Refer to J-STD-020C**

| Item | Ramp-up | Pre-heating | Reflow | Peak Temp | Cooling |
|---|---|---|---|---|---|
| **Temp.scope** | R.T ~ 150 °C | 150°C~200°C | Above 217°C | 260±5°C | Peak Temp.~150 °C |
| **Time spec.** | / | 60~180 sec | 60 ~150 sec | 20~40 sec | / |
| **Time result** | / | 75~100 sec | 90 ~120 sec | 20~35 sec | / |

⚠ **NOTE:**

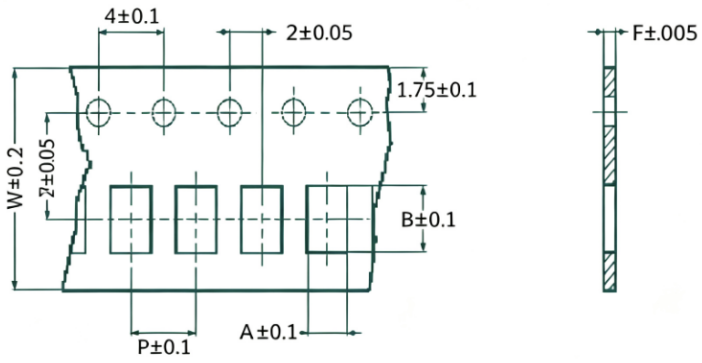
1、Re-flow possible times : within 2 times
2、Nitrogen adopted is recommended while in re-flow
3、Products can only be soldered with reflow

## ⑧ Packaging

### 8.1 Taping Figure



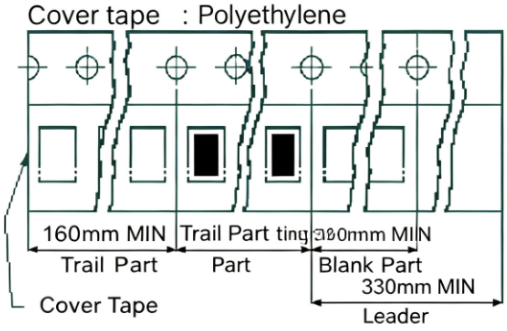

### 8.2 Carrier Tape Dimensions




**Tape Material**

Carrier tape : Paper

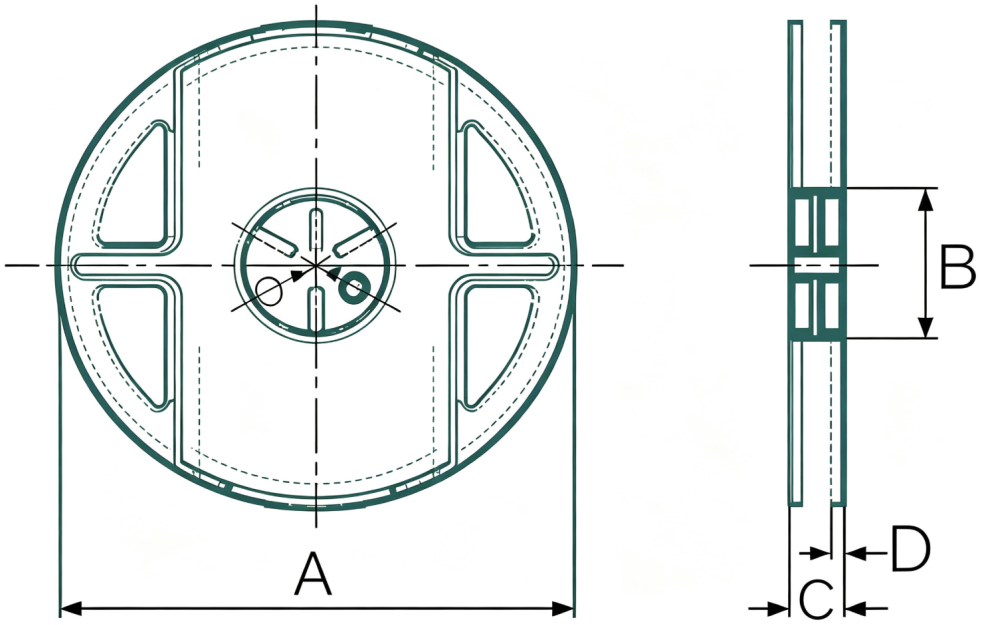
Cover tape : Polyethylene




### Tape Dimensions in mm

| TYPE | A | B | T | W | P | F |
|---|---|---|---|---|---|---|
| 160808 | 1.05 | 1.85 | 0.95 | 8 | 4 | 3.5 |

## 8.3 REEL DIMENSIONS




Tape Dimensions in mm

| TYPE | A | B | C | D |
|---|---|---|---|---|
| 160808 | 178 | 60 | 12 | 1.5 |

## 8.4 Packaging quantities

| TYPE | PCS/REEL |
|---|---|
| 160808 | 4000 |

## ⑨ Rating

### 1, Storage period

Use the products within 12 months after delivered. Solderability should be checked if this period is exceeded.

### 2, Storage conditions

- Storage temperature： -55°C ~ 125°C (after PCB)
- Storage environment: -5°C~40°C, Humidity 40%~70% (before PCB)

### 3, Delivery

Care should be taken when transporting or handling product to avoid excessive vibration or mechanical shock.